

Multilayer Antenna

For 2.4GHz W-LAN & Bluetooth / 5GHz W-LAN

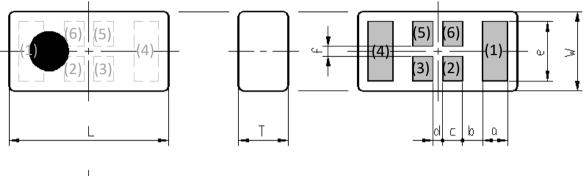
ANT Series 1.6x0.8mm [EIA 0603] TYPE

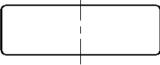
P/N: ANT162442DT-2001A2

Adress: Nihonbashi Dibumu 5:1 Chuo-ku, Tokyo

ANT162442DT-2001A2

SHAPES AND DIMENSIONS





Dimensions (mm)

L	W	Τ	а	b	С	d	е	f
1.60	0.80	0.40	0.215	0.25	0.20	(0.10)	0.63	(0.10)
+/-0.10	+/-0.10	Max	+/-0.10	+/-0.10	+/-0.10		+/-0.10	

Terminal functions

 (2) Feed point (3) Feed point (4) Radiator electrode for 5.5GHz 	(1)	Radiator electrode for 2.4GHz ISM				
(4) Radiator electrode for 5.5GHz	(2)	Feed point				
	(3)	Feed point				
	(4)	Radiator electrode for 5.5GHz				
(5) Feed point	(5)	Feed point				

(6) Feed point

*Terminal (2),(3),(5) and (6) :Connected in inner structure

TERMINATION FINISH

Material	
Au plate	

RF Components

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(Measurement)

TDK Spec

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ELECTRICAL CHARACTERISTICS

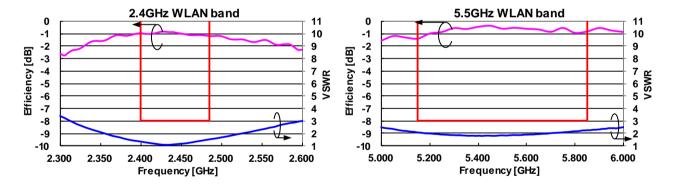
Parameter	Frequency (MHz)			TER Opec		
Farailleter				Min.	Тур.	Max.
VSWR	2400	to	2484	-	1.54	3.0
	5150	to	5850	-	1.58	3.0
Antenna Gain (dBi)**	2400	to	2484	-	2.13	-
	5150	to	5850	-	2.30	-
Polarization					Linear	•
PCB Size (mm)				4	50 x 20)
Antenna keep-out Area (mm)				8x5		
Characteristic Impedance (ohm)				50	(Nomi	nal)

* This is typical antenna performance with the standard PCB.

** Reference value

FREQUENCY CHARACTERISTICS

Note: Tested antenna has been soldered. Evaluation board size is 50x20x1 mm.



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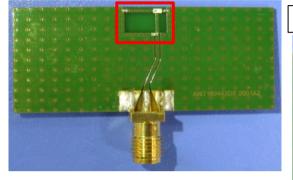
MAXIMUM RATINGS

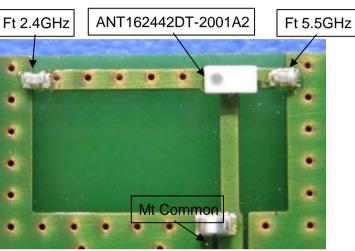
Parameter		TDK Spec	Conditions
Operating temperature (°C)		–40 to +85 °C	
Storage temperature (°C)		–40 to +85 °C	
Power Handling (W) *1		0.8	CW
Human Body Model : HBM	@Each Port (V)	+/-1000	100pF / 1500ohm
Machine Model : MM	@Each Port (V)	+/-150	200pF / 0ohm
Charged Device Model : CDM	@Each Port (V)	+/-500	Humidity : 60%RH max

*1 : Refer to 3GPP TS 38.101-1 V15.2.0

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EVALUATION BOARD





PCB size : 50mm x 20mm x 1mm Antenna area : 8 x 5 mm

Element Value					
Ft 2.4GHz	6.2pF				
Ft 5.5GHz	0.4pF				
Mt Common	1.3nH(MLG1005S1N3C:TDK)				

This evaluation board layout example is defined based on TDK standard.

Other board layouts can be used by optimizing their design.

Matching element values can be selected depending on the board layouts.

Getting more support, please access our website.

https://mytdk.tdk.com/ja/login

The following URL is a link to TDK's simple antenna simulator. <u>https://product.tdk.com/ja/search/rf/rf/antenna/simulation?pid=1000000249778</u>

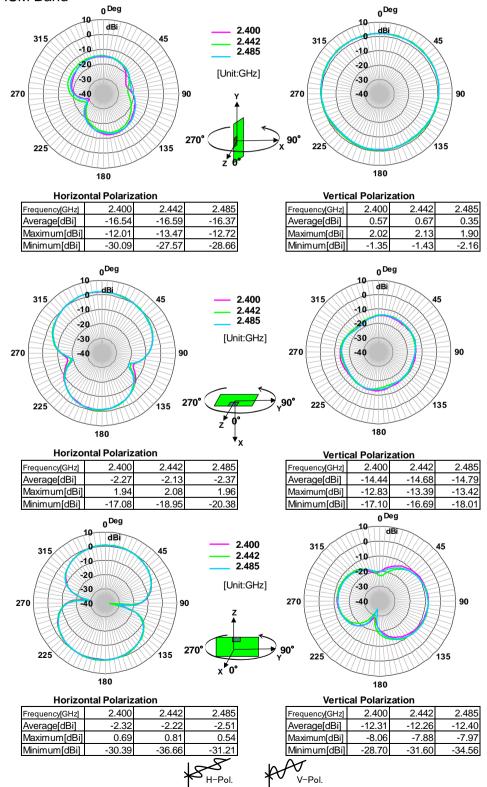
PCB

Measurement condition for Radiation Pattern

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Radiation Pattern

Note: Tested antenna has been soldered. Evaluation board size is 50x20x1 mm. 2.4GHz ISM Band

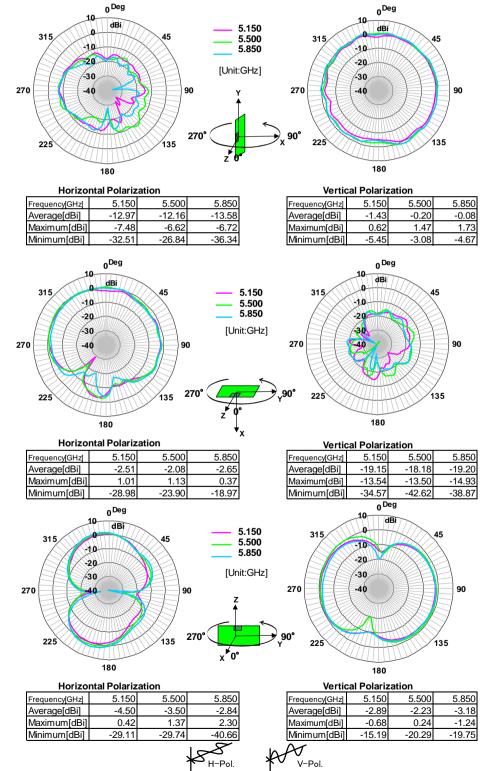


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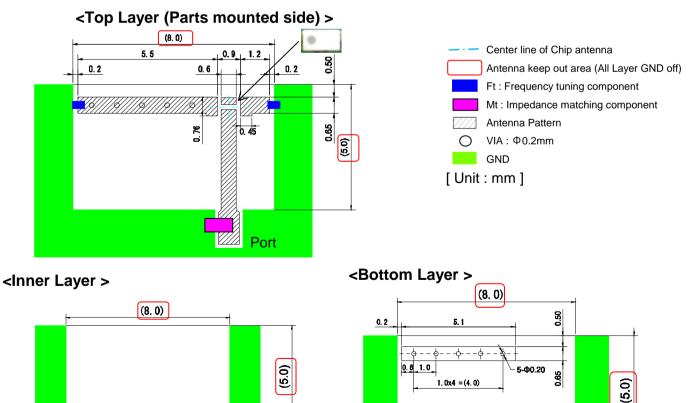
Radiation Pattern

Note: Tested antenna has been soldered. Evaluation board size is 50x20x1 mm. 5.5GHz Band



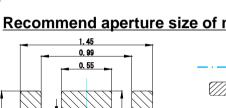
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Example of Antenna pattern layout (TDK Standard PCB)



o' o. o'

Recommend aperture size of metal mask for solder printing



Center line of Chip Aperture of metal

RECOMMENDED LAND PATTERN

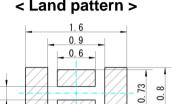
Recommend land pattern and solder resist pattern

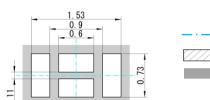
< Land pattern >

21 <u>.</u>

0.65

9





< Solder resist pattern >

Center line of Chip Land Pattern **Resist Pattern**

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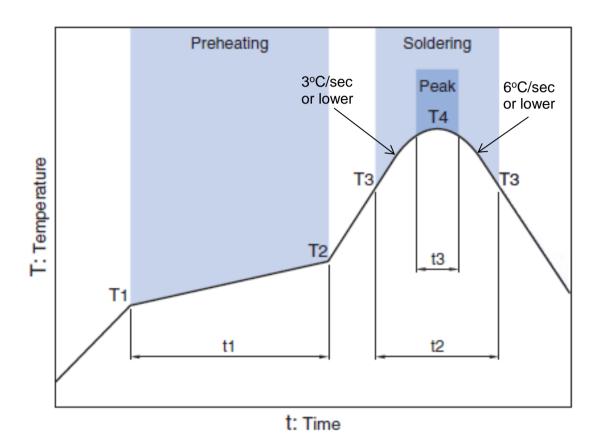
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ENVIROMENT INFORMATION

RoHS Statement RoHS Compliance

TDK Corporation

RECOMMENDED REFLOW PROFILE



	Prohe	ating	Soldering					
Preheating		Critical zon	e (T3 to T4)	Peak				
Ter	np.	Time	Temp.	Time	Temp.	Time		
T1	T2	t1	Т3	t2	T4	t3 *		
150°C	200°C	60 to 120sec	217°C	60 to 120sec	240 to 260°C	30 sec Max		

* t3 : Time within 5°C of actual peak temperature

The maximum number of reflow is 3.

Note: Lead free solder is recommended. Recommended solder is Sn-3.0Ag-0.5Cu. (M705 by Senju Metal Industry) **RF** Components

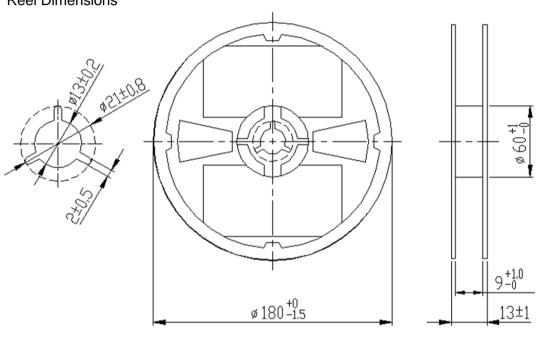
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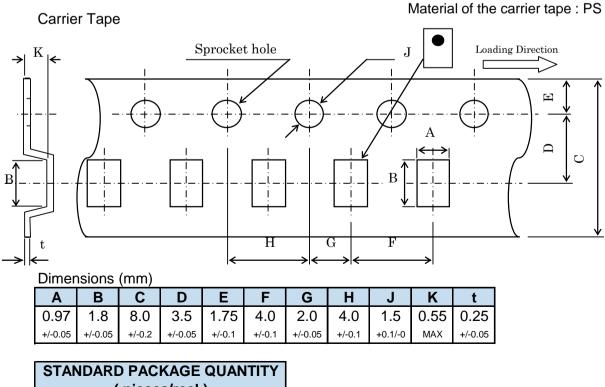
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PACKAGING STYLE

Reel Dimensions



Dimensions in mm



(pieces/reel)

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REMINDERS FOR USING THESE PRODUCTS

Before using these products, be sure to request the delivery specifications.

SAFETY REMINDERS

Please pay sufficient attention to the warnings for safe designing when using these products.

The products listed on this specification sheet are intended for use in general electronic equipment (AV equipment, telecommunications equipment, home appliances, amusement equipment, computer equipment, personal equipment, office equipment, measurement equipment, industrial robots) under a normal operation and use condition.

The products are not designed or warranted to meet the requirements of the applications listed below, whose performance and/or quality require a more stringent level of safety or reliability, or whose failure, malfunction or trouble could cause serious damage to society, person or property. Please understand that we are not responsible for any damage or liability caused by use of the products in any of the applications below or for any other use exceeding the range or conditions set forth in this specification sheet.

- 1. Aerospace/Aviation equipment
- 2. Transportation equipment (cars, electric trains, ships, etc.)
- 3. Medical equipment
- 4. Power-generation control equipment
- 5. Atomic energy-related equipment
- 6. Seabed equipment
- 7. Transportation control equipment
- 8. Public information-processing equipment
- 9. Military equipment
- 10. Electric heating apparatus, burning equipment
- 11. Disaster prevention/crime prevention equipment
- 12. Safety equipment
- 13. Other applications that are not considered general-purpose applications

When using this product in general-purpose applications, you are kindly requested to take into consideration securing protection circuit/equipment or providing backup circuits, etc., to ensure higher safety.